

**10/552429**

**JCO5 Rec'd PCT/PTO 07 OCT 2005**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re: Application of David T. Beatson et al.

Examiner **N/A**

Application No. **Not yet Assigned**

Group Art Unit **N/A**

Filed **Herewith**

Atty. Docket No. **P26229-A USA**

**ELECTRICAL INTERCONNECT STRUCTURES FOR INTEGRATED CIRCUITS AND METHODS OF MANUFACTURING THE SAME**

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**CERTIFICATE OF MAILING**

I hereby certify that this correspondence, along with any other papers indicated as being enclosed, is being deposited with the United States Postal Services, as first class mail, postage prepaid, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on October 7, 2005.

Andrea Cojocar

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Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**INFORMATION DISCLOSURE**  
**STATEMENT PURSUANT TO 37 C.F.R. §1.97(a)**

Sir:

It is requested respectfully that the information identified on the enclosed Form PTO-1449 (Modified) be made of record and considered with respect to the above-referenced patent application.

This Information Disclosure Statement accompanies the new patent application submitted herewith.

PATENT

**10/552429**  
**1005 Rec'd PCT/PTO 07 OCT 2005**

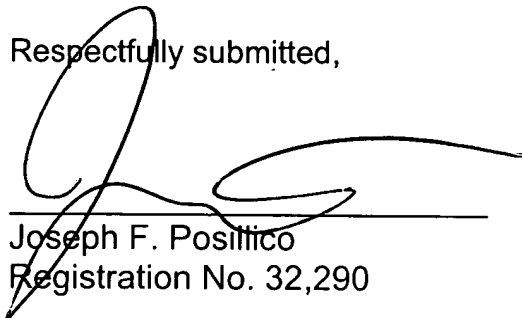
Application Serial No. 10/679,806  
Attorney Docket No. P26,257-C USA

The Examiner is requested to indicate that each item on the enclosed Form PTO-1449 (Modified) has been considered by initialing and dating the enclosed Form and returning a copy of same to the undersigned.

Identification of information on the attached Form, or in this statement, is not an admission that such information is prior art to the invention claimed in the present application or that such information is in an analogous art area.

The Commissioner is authorized hereby to charge any fees or credit any overpayment associated with this Statement (copy enclosed) to Deposit Account Number 19-5425.

Respectfully submitted,



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Date: October 7, 2005

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10/552429

FORM PTO-1449 (MODIFIED)

INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT

APPLICATION NO.	N/A
FILING DATE	Herewith
FIRST NAMED INVENTOR	David T. Beatson
ART UNIT	N/A
EXAMINER NAME	N/A
ATTORNEY DOCKET NO.	P26229-A USA

U.S. PATENT DOCUMENTS

EXAMINER INITIALS		DOCUMENT NO.	PUBLICATION DATE	NAME
	AA	6,885,104	April 26, 2005	Ellis , et al.
	AB	6,599,561	July 29, 2003	Dow , et al.
	AC	6,534,877	March 18, 2003	Ellis , et al.
	AD	6,413,576	July 2, 2002	Ellis , et al.
	AE	6,352,743	March 5, 2002	Ellis , et al.
	AF	6,156,990	December 5, 2000	Ellis
	AG			

FOREIGN PATENT DOCUMENTS

EXAMINER INITIALS		DOCUMENT NO.	PUBLICATION DATE	COUNTRY
	BA	WO 01/01478 A	January 4, 2001	PCT
	BB	PCT/US2004/087150 A1	May 6, 2004	PCT
	BC	PCT/ US2004/155702 A 1	October 24, 2002	PCT
	BD	PCT/US2002/168845 A1	November 14, 2002	PCT
	BE	WO 01/01478 A	April 01, 2001	PCT
	BF	PCT/US2004/087150	June 5, 2004	PCT
	BG	PCT/US2002/155702 A1	October 10, 2002	PCT
	BH	PCT/US/2002/168845 A1	November 11, 2002	PCT
	BI			

10/552429

## OTHER PUBLICATIONS

	CA	Noguchi J. et al: "Effect of NH <sub>3</sub> -Plasma Treatment and CMP Modification on TDDB Improvement in U Metallization", IEEE Transaction on Electron Devices, vol. 48, no. 7, IEEE Inc. NY, US, July 2001.
	CB	Maruyama T.; Morishita T. "Copper Nitride Thin Films Prepared by Radio Frequency Reactive Sputtering" J. Appl. Physics, vol. 78, no. 6, September 1995.
	CC	

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EXAMINER

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DATE CONSIDERED

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**EXAMINER:** Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformation and not considered. Include copy of this form with next communication to applicant.